

Electronic Patent Application Fee Transmittal

Application Number:	10585461
Filing Date:	27-May-2009
Title of Invention:	Circuit connection material, film-shaped circuit connection material using the same, circuit member connection structure, and manufacturing method thereof
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Filer:	William Ivan Solomon/Kelli Harris
Attorney Docket Number:	1303.46354X00

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Claims in excess of 20	1615	2	60	120
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 2 months with \$0 paid	1252	1	560	560
Miscellaneous:				
Total in USD (\$)				680